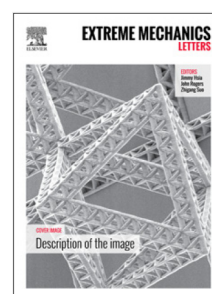


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Advanced Approaches for Quantitative Characterization of Thermal Transport Properties in Soft Materials Using Thin, Conformable Resistive Sensors

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